

WHAT IS CLAIMED IS:

1 1. A process for cleaning paste residue from a workpiece
2 comprising the step of electrolytically contacting the
3 workpiece with an aqueous solution containing 0.2 to 2 weight
4 percent TMAH.

1 2. The process of claim 1 wherein the step of
2 electrolytically contacting comprises spraying the workpiece
3 with the aqueous solution.

1 3. The process of claim 1 wherein the step of
2 electrolytically contacting comprises immersing the workpiece
3 in the aqueous solution.

1 4. The process of claim 1 wherein the aqueous solution in the
2 step of electrolytically contacting is maintained at a
3 temperature of 25 to 80 °C.

1 5. The process of claim 1 wherein the aqueous solution in the
2 step of electrolytically contacting is maintained at a
3 temperature of 70 °C.

1 6. The process of claim 1 wherein the aqueous solution in the
2 step of electrolytically contacting contains 0.4 to 0.5 weight
3 percent TMAH.

1 7. The process of claim 1 further comprising the step, prior
2 to the step of electrolytically contacting, of
3 nonelectrolytically contacting the workpiece with an aqueous
4 solution containing 0.2 to 2 weight percent TMAH.

1 8. The process of claim 7 wherein the step of
2 nonelectrolytically contacting comprises spraying the
3 workpiece with the aqueous solution.

1 9. The process of claim 7 wherein the step of
2 nonelectrolytically contacting comprises immersing the
3 workpiece in the aqueous solution.

1 10. The process of claim 7 wherein the aqueous solution in
2 the step of nonelectrolytically contacting is maintained at a
3 temperature of 25 to 80 °C.

1 11. The process of claim 7 wherein the aqueous solution in
2 the step of nonelectrolytically contacting is maintained at a
3 temperature of 70 °C.

1 12. The process of claim 1 wherein the workpiece is a
2 screening mask.

1 13. The process of claim 1 wherein the paste comprises
2 solder.

1 14. The process of claim 1 wherein the paste comprises at
2 least one metal selected from the group consisting of
3 molybdenum, copper, tungsten, nickel, gold, palladium,
4 platinum and silver.

1 15. The process of claim 1 wherein the paste residue
2 comprises an inorganic material selected from the group
3 consisting of ceramic and glass.

1 16. The process of claim 1 wherein the paste comprises a
2 polymeric binder.